



Maskless Lithography and Multibeam Mask Writer Workshop
May 10, 2010
Agenda

8:30 AM – 9:00 AM	Continental Breakfast	
9:00 AM – 9:10 AM	Welcome	<i>L. Litt, GLOBALFOUNDRIES/SEMATECH G. Hughes, SEMATECH</i>
9:10 AM – 9:30 AM	ML2 Wafer Writer Overview	<i>L. Litt, GLOBALFOUNDRIES/SEMATECH</i>
9:30 AM – 11:00 AM	Supplier Presentations	<i>B.J. Kampherbeek, MAPPER Lithography C. Bevis, KLA-Tencor A. Yamada, Advantest H. Smith, LumArray</i>
11:00 AM – 12:30 PM	Customer User Perspective	<i>J.H. Chen, TSMC L. Pain, CEA-Leti Y. Borodovsky, Intel*</i>
12:30 PM – 1:30 PM	Lunch	
1:30 PM – 2:15 PM	Breakout	<i>L. Litt, GLOBALFOUNDRIES/SEMATECH G. Hughes, SEMATECH</i>
2:15 PM – 2:45 PM	Mask Pattern Generator Overview	<i>G. Hughes, SEMATECH</i>
2:45 PM – 3:45 PM	Supplier Presentations	<i>M. Slodowski, Vistec Electron Beam GmbH M. Yamabe, ASET H. Yasuda, PARAM</i>
3:45 PM – 4:45 PM	Customer Perspective	<i>N. Hayashi, Dai Nippon Printing F. Kalk, Toppan</i>
4:45 PM – 5:30 PM	Breakout	<i>G. Hughes, SEMATECH L. Litt, GLOBALFOUNDRIES/SEMATECH</i>
5:30 PM	Summary and Conclusions	<i>G. Hughes, SEMATECH L. Litt, GLOBALFOUNDRIES/SEMATECH</i>

* *ML2 and MBMW*

Accelerating the next technology revolution.